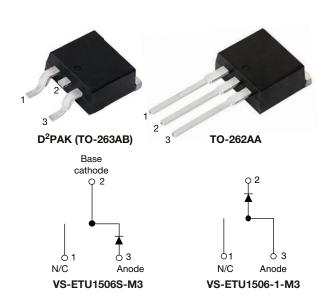


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HALOGEN

Ultrafast Rectifier, 15 A FRED Pt®



PRIMARY CHARACTERISTICS							
I _{F(AV)}	15 A						
V_{R}	600 V						
V _F at I _F	1.1 V						
t _{rr} (typ.)	24 ns						
T _J max.	175 °C						
Package	D ² PAK (TO-263AB), TO-262AA						
Circuit configuration	Single						

FEATURES

- Low forward voltage drop
- · Ultrafast recovery time
- 175 °C operating junction temperature
- Low leakage current
- FREE Designed and qualified according to JEDEC®-JESD 47
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

State of the art, ultralow V_F, soft-switching ultrafast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units, and DVD AC/DC power supplies.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V_{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 143 °C	15	۸			
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	160	А			
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-		
Forward voltage	V _F	I _F = 15 A	=.	1.35	1.9	V	
	VF	I _F = 15 A, T _J = 150 °C	=.	1.1	1.3		
Devenue legicade evenuent	,	V _R = V _R rated	=.	0.01	15		
Reverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	=.	20	200	μΑ	
Junction capacitance	C _T	V _R = 600 V	-	12	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nΗ	



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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time		$I_F = 1 A, dI_F/dt = 1$	$I_F = 1 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$			28		
		$I_F = 15 \text{ A}, dI_F/dt =$	100 A/μs, V _R = 30 V	-	36	47	no	
	t _{rr}	T _J = 25 °C		-	40	-	ns	
		T _J = 125 °C	I _F = 15 A dI _F /dt = 200 A/μs V _R = 390 V	ı	87	ı		
Dook room ourrent	I _{RRM}	T _J = 25 °C		-	5	-	Α	
Peak recovery current		T _J = 125 °C		-	9.0	-		
Reverse recovery charge	0	T _J = 25 °C	VR = 390 V	-	107	-	С	
neverse recovery charge	Q_{rr}	T _J = 125 °C		-	430	-		
Reverse recovery time	t _{rr}		I _E = 15 A	-	53	-	ns	
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = 800 A/\mu s$	-	25	ı	Α	
Reverse recovery charge	Q_{rr}		V _R = 390 V	-	730	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C		
Thermal resistance, junction-to-case	R _{thJC}		-	1.3	1.51	°C/W		
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	-	-	70			
Thermal resistance, case-to-heat sink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-			
Weight			-	2.0	-	g		
Weight			-	0.07	-	oz.		
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)		
Manding design		Case style D ² PAK (TO-263AB)	O-263AB) ETU1506S					
Marking device		Case style TO-262		ETU1	506-1			

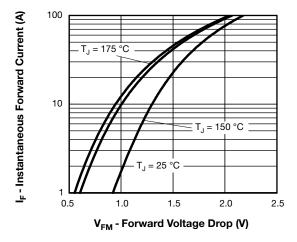


Fig. 1 - Typical Forward Voltage Drop Characteristics

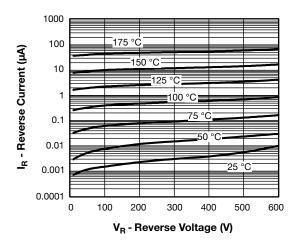


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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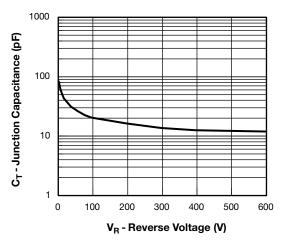


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

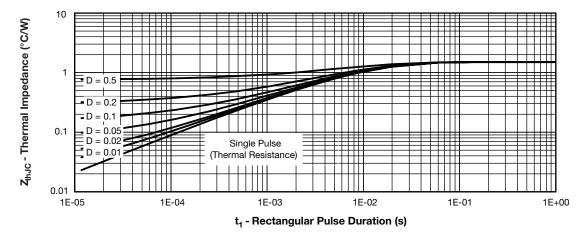


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

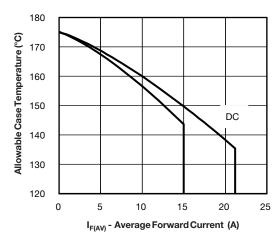


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

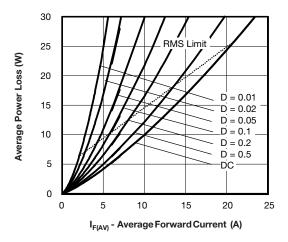


Fig. 6 - Forward Power Loss Characteristics



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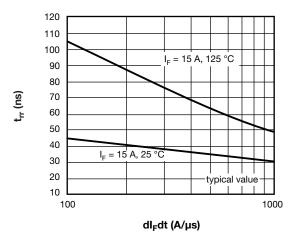


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

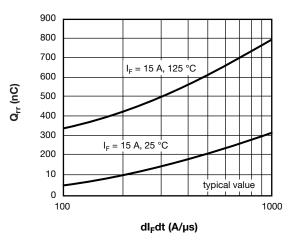


Fig. 8 - Typical Stored Charge vs. dl_E/dt

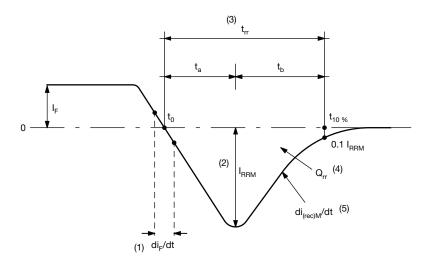


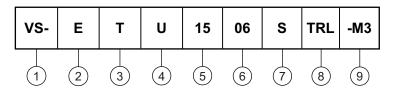
Fig. 9 - Reverse Recovery Waveform and Definitions

VS-ETU1506S-M3, VS-ETU1506-1-M3

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ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

Circuit configuration E = single diode

T = TO-220

3 4 5 U = ultrafast recovery time

Current code (15 = 15 A)

Voltage code (06 = 600 V)

• $S = D^2PAK (TO-263AB)$

• -1 = TO-262AA

8 • None = tube (50 pieces)

• TRL = tape and reel (left oriented, for D²PAK (TO-263AB) package)

• TRR = tape and reel (right oriented, for D²PAK (TO-263AB) package)

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free 9

ORDERING INFORMATION (Example)						
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION				
VS-ETU1506S-M3	50	Antistatic plastic tubes				
VS-ETU1506STRR-M3	800	13" diameter plastic tape and reel				
VS-ETU1506STRL-M3	800	13" diameter plastic tape and reel				
VS-ETU1506-1-M3	50	Antistatic plastic tubes				

LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164				
Differsions	TO-262AA	www.vishay.com/doc?96165				
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
	TO-262AA	www.vishay.com/doc?95443				
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?96424				
SPICE model		www.vishay.com/doc?96132				



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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES		SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STWBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

Revision: 13-Jul-17 Document Number: 96164



Vishay Semiconductors

TO-262AA

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262







⊕ 0.010 **M** A**M** B

Lead assignments



Diodes 1. - Anode (two die)/open (one die)

2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

SYMBOL	MILLIM	IETERS	INC	HES	NOTES			
OTHIBOL	MIN.	MAX.	MIN.	MAX.	NOTES			
Α	4.06	4.83	0.160	0.190				
A1	2.03	3.02	0.080	0.119				
b	0.51	0.99	0.020	0.039				
b1	0.51	0.89	0.020	0.035	4			
b2	1.14	1.78	0.045	0.070				
b3	1.14	1.73	0.045	0.068	4			
С	0.38	0.74	0.015	0.029				
c1	0.38	0.58	0.015	0.023	4			
c2	1.14	1.65	0.045	0.065				
D	8.51	9.65	0.335	0.380	2			
D1	6.86	8.00	0.270	0.315	3			
Е	9.65	10.67	0.380	0.420	2, 3			
E1	7.90	8.80	0.311	0.346	3			
е	2.54	BSC	0.100) BSC				
L	13.46	14.10	0.530	0.555				
L1	-	1.65	-	0.065	3			
L2	3.56	3.71	0.140	0.146				

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
 (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- Controlling dimension: inches
- Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)



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